

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) An optical communications module comprising:  
~~one or more~~ a plurality of dielectric wiring substrates and a chassis,  
said ~~one or more~~ plurality of dielectric wiring substrates having an optical transmitter section, an optical receiver section, or an optical transceiver section provided thereon, ~~the chassis encasing all of the dielectric wiring substrates including said optical transmitter section, said optical receiver section or said optical transceiver section provided thereon,~~  
at least ~~one~~ two of said dielectric wiring substrates having a metal part formed on one side thereof, said dielectric substrates forming an outer wall of the chassis, said metal part being exposed as an outermost surface of the chassis.
2. (Previously Presented) An optical communications module according to claim 1, wherein said at least one dielectric wiring substrate having the metal part formed on one side thereof comprises a metal base substrate.
3. (Previously Presented) An optical communications module according to claim 1, wherein said dielectric wiring substrates are thermally connected together through a metal part of said chassis.
4. (Previously Presented) An optical communications module according to claim 1, wherein said dielectric wiring substrates are thermally separated from each other.

5. (Original) An optical communications module according to claim 1, wherein said chassis has one or more vents.

6. (Previously Presented) An optical communications module according to claim 1, wherein said one or more dielectric wiring substrates comprise multilayer wiring substrates and an exposed surface of a grounding layer thereof has a metal plate adhered thereto, said metal plate being in thermal contact with the metal part of the chassis.

7. (Previously Presented) An optical communications module according to claim 1, wherein said dielectric wiring substrates comprise multilayer wiring substrates, and an grounding layer thereof has a heatsink provided on its exposed surface.

8. (Previously Presented) An optical communications module according to claim 1, wherein the metal part formed on one side of said one or more dielectric wiring substrates is partially removed, exposing terminals or other components of said optical transmitter section, optical receiver section, or optical transceiver section, through the removed portion to the outside of the optical communications module.